



PMEG3002EJ

30 V, 200 mA low VF Schottky barrier rectifier

1 November 2023

Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD323F (SC-90) small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 0.2$ A
- Reverse voltage: $V_R \leq 30$ V
- Low forward voltage
- Small and flat lead SMD plastic package
- AEC-Q101 qualified

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch Mode Power Supply (SMPS)
- Reverse polarity protection
- Ultra high-speed switching
- Low power consumption applications

4. Quick reference data



Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------|-------------------------|---|-----|-----|-----|---------|
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$; $f = 20$ kHz; square wave; $T_{amb} \leq 135$ °C | - | - | 0.2 | A |
| | | $\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 145$ °C | - | - | 0.2 | A |
| V_R | reverse voltage | $T_j = 25$ °C | - | - | 30 | V |
| V_F | forward voltage | $I_F = 200$ mA; $T_j = 25$ °C | - | 420 | 480 | mV |
| I_R | reverse current | $V_R = 30$ V; $T_j = 25$ °C | - | 10 | 40 | μ A |

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline | Graphic symbol |
|-----|--------|-------------|--|---|
| 1 | K | cathode[1] |  SC-90 (SOD323F) |  sym001 |
| 2 | A | anode | | |

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|----------------------------|---------|---|-------------------------|
| | Name | Description | Version |
| PMEG3002EJ | SC-90 | plastic, surface-mounted package; 2 leads; 1.7 mm x 1.25 mm x 0.7 mm body | SOD323F |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMEG3002EJ | 1M |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | | Min | Max | Unit |
|-------------|-------------------------------------|--|---------|-----|-------|------|
| V_R | reverse voltage | $T_j = 25\text{ °C}$ | | - | 30 | V |
| $I_{F(AV)}$ | average forward current | $\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{amb} \leq 135\text{ °C}$ | [1] | - | 0.2 | A |
| | | $\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 145\text{ °C}$ | | - | 0.2 | A |
| I_{FRM} | repetitive peak forward current | $t_p \leq 1\text{ ms}$; $\delta \leq 0.25$ | | - | 2.6 | A |
| I_{FSM} | non-repetitive peak forward current | $t_p = 8\text{ ms}$; square wave; $T_j = 25\text{ °C}$ prior to surge; $T_{j(init)} = 25\text{ °C}$ | | - | 2.75 | A |
| P_{tot} | total power dissipation | $T_{amb} \leq 25\text{ °C}$ | [2] [3] | - | 385 | mW |
| | | | [2] [4] | - | 695 | mW |
| | | | [5] [2] | - | 1.045 | W |
| T_j | junction temperature | | | - | 150 | °C |
| T_{amb} | ambient temperature | | | -55 | 150 | °C |
| T_{stg} | storage temperature | | | -65 | 150 | °C |

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

[5] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | | Min | Typ | Max | Unit |
|----------------|--|-------------|-------------|-----|-----|-----|------|
| $R_{th(j-a)}$ | thermal resistance from junction to ambient | in free air | [1] [2] [3] | - | - | 325 | K/W |
| | | | [1] [2] [4] | - | - | 180 | K/W |
| | | | [1] [2] [5] | - | - | 120 | K/W |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point | | [6] | - | - | 25 | K/W |

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Reflow soldering is the only recommended soldering method.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [5] Device mounted on a ceramic PCB, Al₂O₃, standard footprint.
- [6] Soldering point of cathode tab.

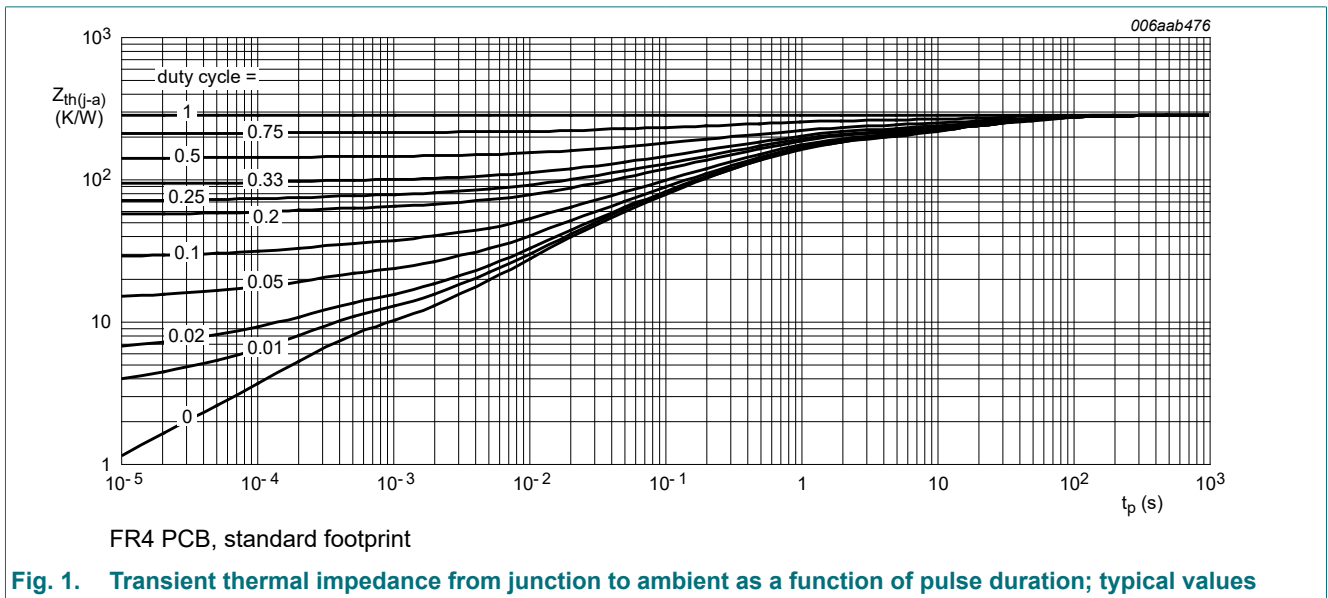


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

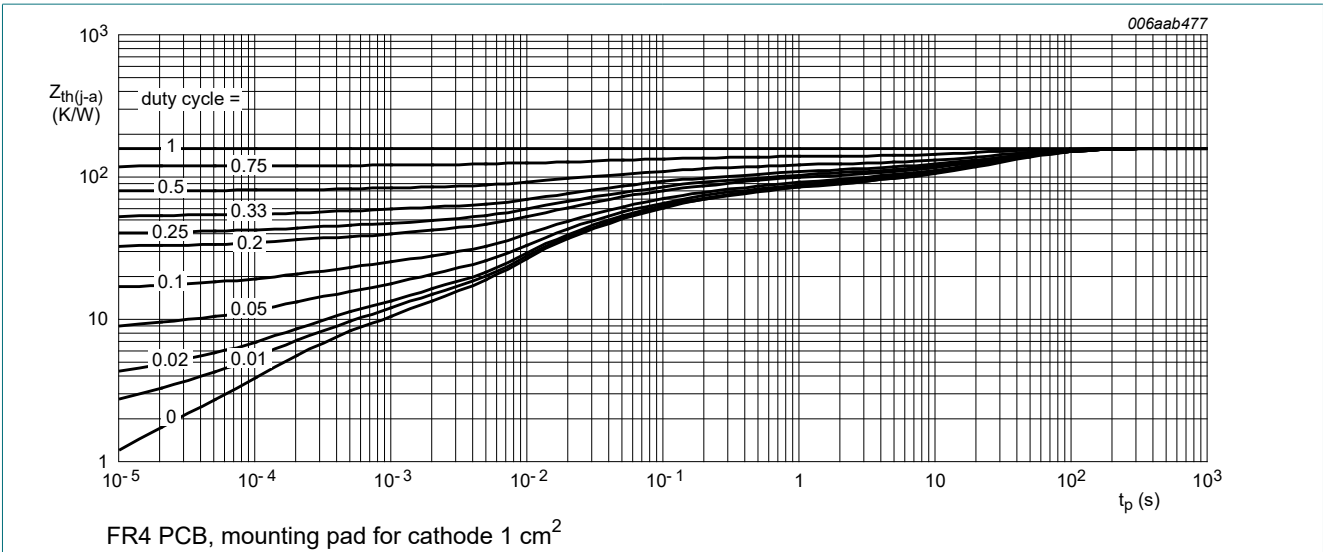


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

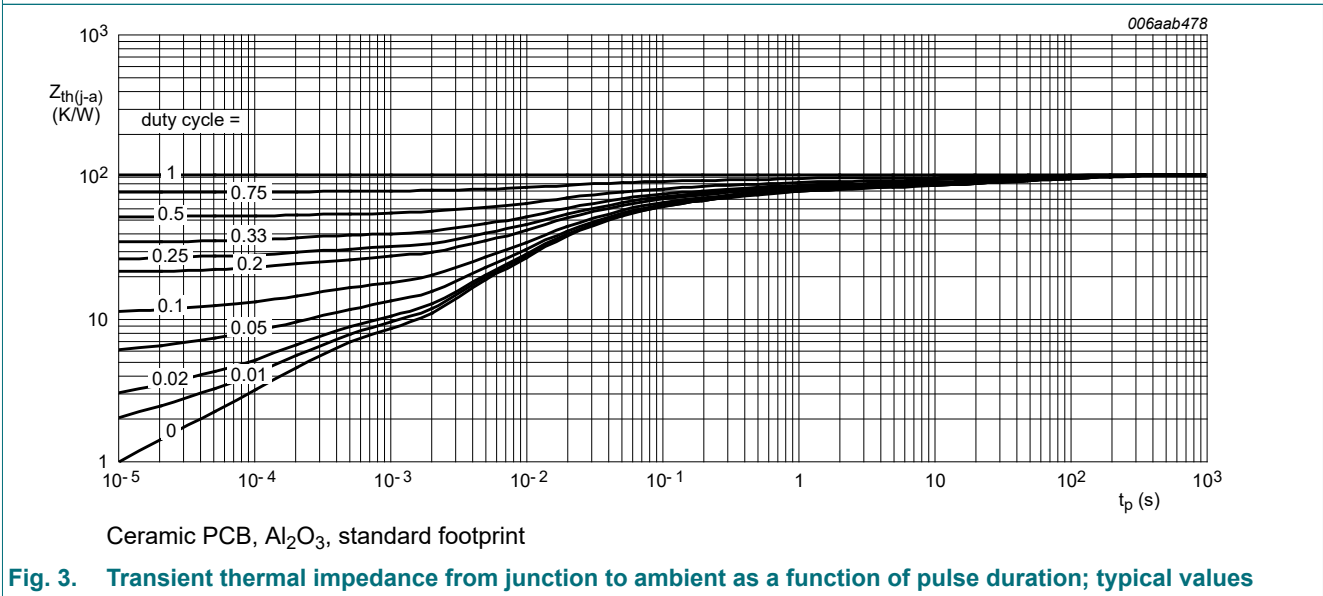
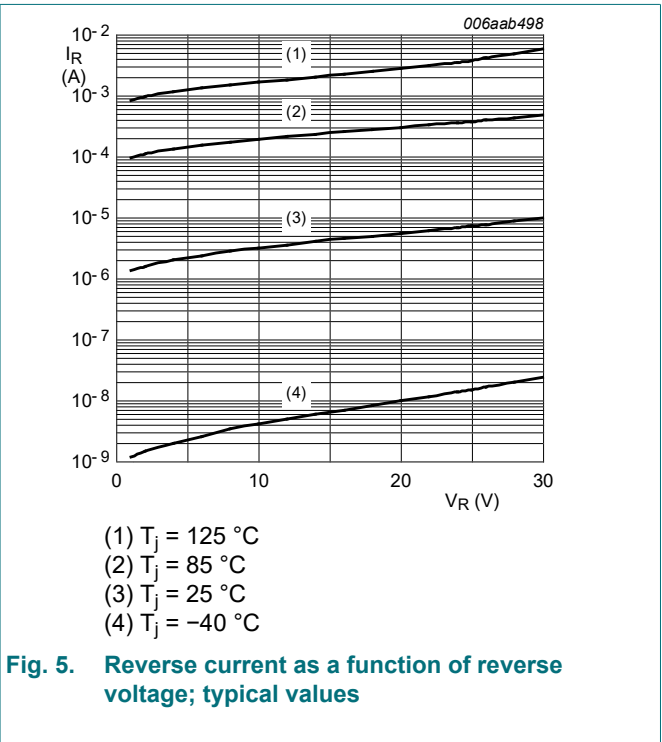
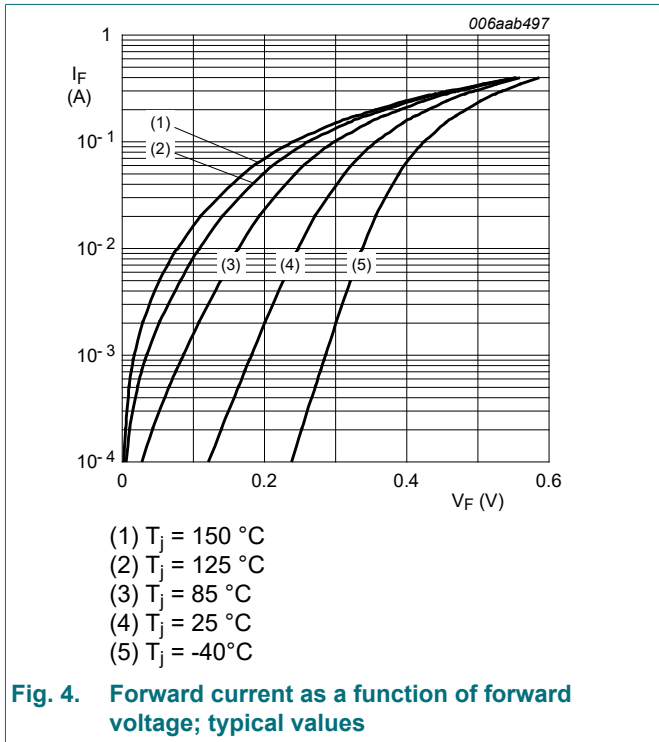


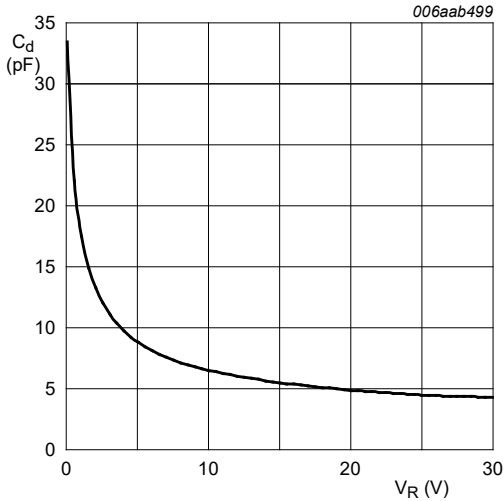
Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

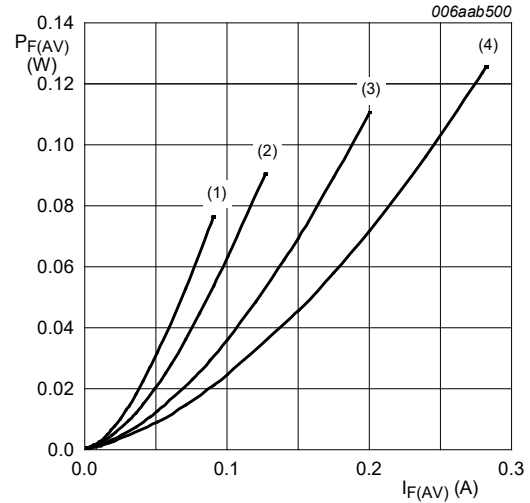
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|----------|-----------------------|--|-----|-----|-----|---------------|
| V_F | forward voltage | $I_F = 0.1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 130 | 190 | mV |
| | | $I_F = 1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 190 | 250 | mV |
| | | $I_F = 10 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 250 | 300 | mV |
| | | $I_F = 100 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 355 | 400 | mV |
| | | $I_F = 200 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 420 | 480 | mV |
| I_R | reverse current | $V_R = 10 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 2.5 | 10 | μA |
| | | $V_R = 30 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$ | - | 10 | 40 | μA |
| C_d | diode capacitance | $V_R = 1 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$ | - | 18 | - | pF |
| | | $V_R = 10 \text{ V}; f = 1 \text{ MHz}; T_j = 25 \text{ }^\circ\text{C}$ | - | 7 | - | pF |
| t_{rr} | reverse recovery time | When switched from $I_F = 10 \text{ mA}$ to $I_R = 10 \text{ mA}; R_L = 100 \text{ } \Omega$; measured at $I_R = 1 \text{ mA}; T_j = 25 \text{ }^\circ\text{C}$ | - | 5 | - | ns |





$f = 1 \text{ MHz}; T_{\text{amb}} = 25 \text{ }^{\circ}\text{C}$

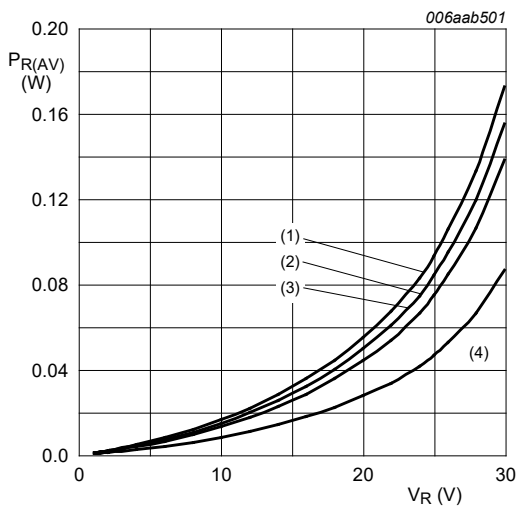
Fig. 6. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^{\circ}\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

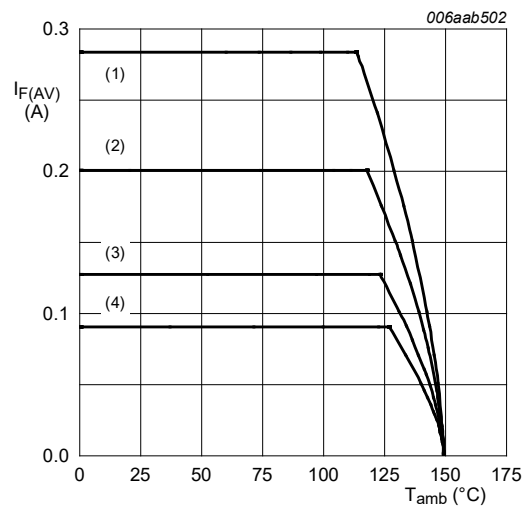
Fig. 7. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^{\circ}\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig. 8. Average reverse power dissipation as a function of reverse voltage; typical values

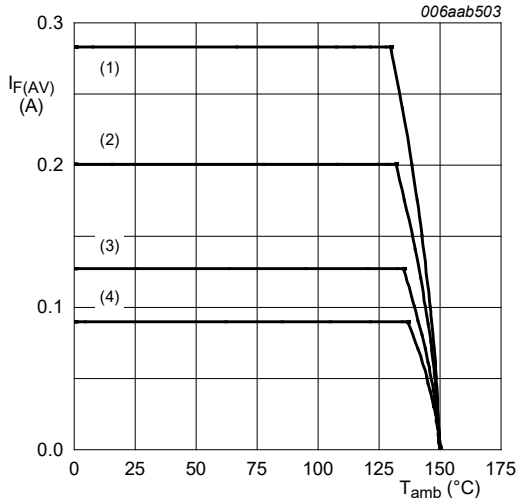


FR4 PCB, standard footprint

$T_j = 150 \text{ }^{\circ}\text{C}$

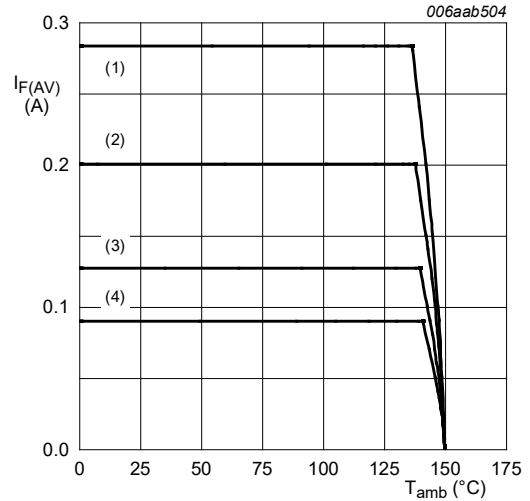
- (1) $\delta = 1; \text{DC}$
- (2) $\delta = 0.5; f = 20 \text{ kHz}$
- (3) $\delta = 0.2; f = 20 \text{ kHz}$
- (4) $\delta = 0.1; f = 20 \text{ kHz}$

Fig. 9. Average forward current as a function of ambient temperature; typical values



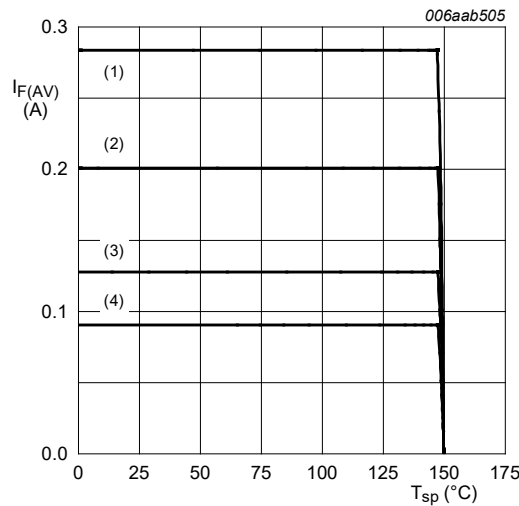
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 10. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

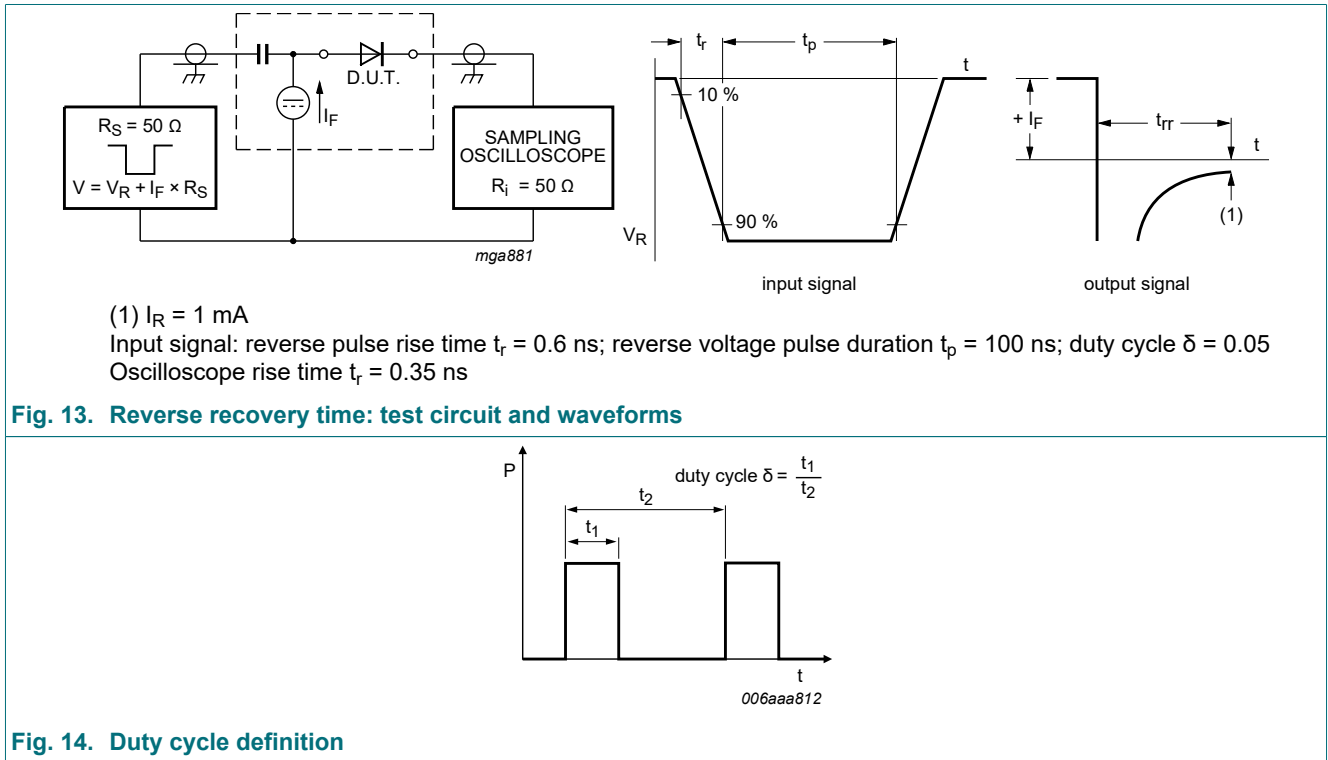
Fig. 11. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$
 (1) $\delta = 1$; DC
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of solder point temperature; typical values

11. Test information



The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current}$$

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

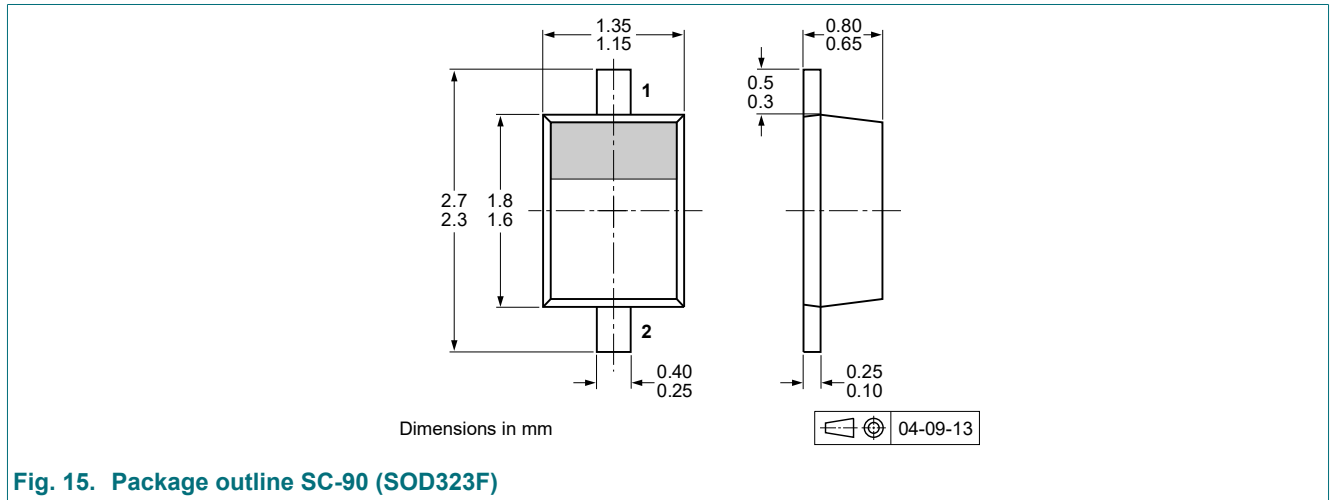


Fig. 15. Package outline SC-90 (SOD323F)

13. Soldering

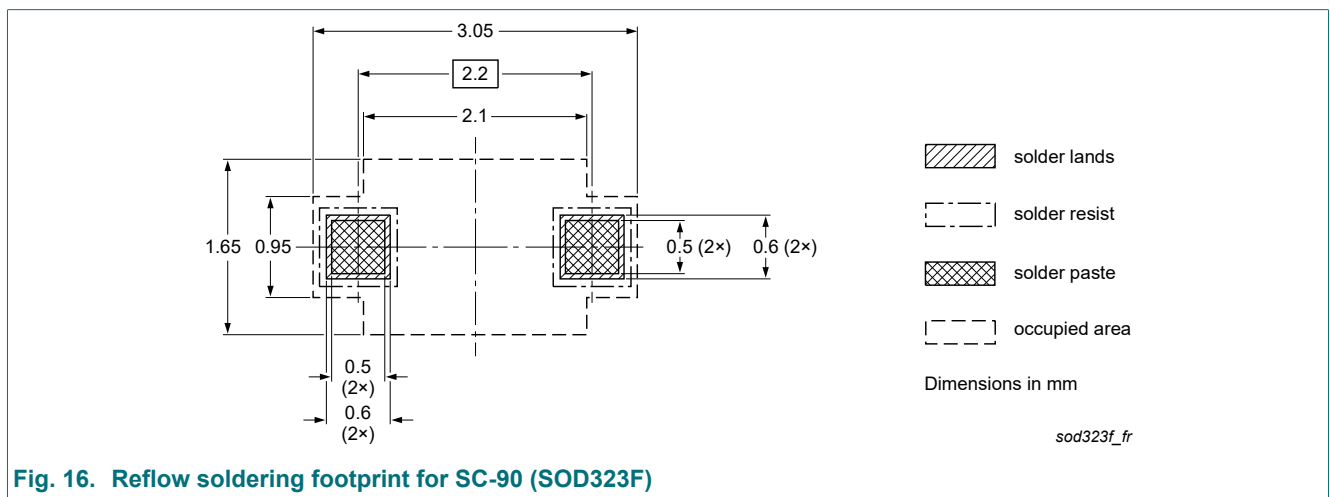


Fig. 16. Reflow soldering footprint for SC-90 (SOD323F)

14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status | Change notice | Supersedes |
|----------------|---|--------------------|---------------|----------------|
| PMEG3002EJ v.2 | 20231101 | Product data sheet | - | PMEG3002EJ v.1 |
| Modifications: | <ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.Legal texts have been adapted to the new company name where appropriate.Section "Packing information" removed. | | | |
| PMEG3002EJ v.1 | 20090515 | Product data sheet | - | - |

15. Legal information

Data sheet status

| Document status [1][2] | Product status [3] | Definition |
|--------------------------------|--------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

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